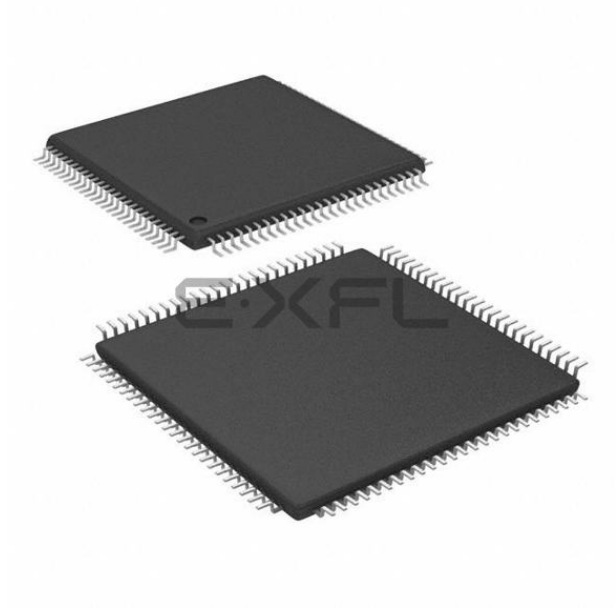

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Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	84
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
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TABLE 4-7: INPUT CAPTURE REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IC1BUF	0140	Input 1 Capture Register																xxxx
IC1CON	0142	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI1	ICI0	ICOV	ICBNE	ICM2	ICM1	ICM0	0000
IC2BUF	0144	Input 2 Capture Register																xxxx
IC2CON	0146	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI1	ICI0	ICOV	ICBNE	ICM2	ICM1	ICM0	0000
IC3BUF	0148	Input 3 Capture Register																xxxx
IC3CON	014A	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI1	ICI0	ICOV	ICBNE	ICM2	ICM1	ICM0	0000
IC4BUF	014C	Input 4 Capture Register																xxxx
IC4CON	014E	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI1	ICI0	ICOV	ICBNE	ICM2	ICM1	ICM0	0000
IC5BUF	0150	Input 5 Capture Register																xxxx
IC5CON	0152	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI1	ICI0	ICOV	ICBNE	ICM2	ICM1	ICM0	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-8: OUTPUT COMPARE REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
OC1RS	0180	Output Compare 1 Secondary Register																xxxx
OC1R	0182	Output Compare 1 Register																xxxx
OC1CON	0184	—	—	OCSIDL	—	—	—	—	—	—	—	—	OCFLT	OCTSEL	OCM2	OCM1	OCM0	0000
OC2RS	0186	Output Compare 2 Secondary Register																xxxx
OC2R	0188	Output Compare 2 Register																xxxx
OC2CON	018A	—	—	OCSIDL	—	—	—	—	—	—	—	—	OCFLT	OCTSEL	OCM2	OCM1	OCM0	0000
OC3RS	018C	Output Compare 3 Secondary Register																xxxx
OC3R	018E	Output Compare 3 Register																xxxx
OC3CON	0190	—	—	OCSIDL	—	—	—	—	—	—	—	—	OCFLT	OCTSEL	OCM2	OCM1	OCM0	0000
OC4RS	0192	Output Compare 4 Secondary Register																xxxx
OC4R	0194	Output Compare 4 Register																xxxx
OC4CON	0196	—	—	OCSIDL	—	—	—	—	—	—	—	—	OCFLT	OCTSEL	OCM2	OCM1	OCM0	0000
OC5RS	0198	Output Compare 5 Secondary Register																xxxx
OC5R	019A	Output Compare 5 Register																xxxx
OC5CON	019C	—	—	OCSIDL	—	—	—	—	—	—	—	—	OCFLT	OCTSEL	OCM2	OCM1	OCM0	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.3.2 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

The TBLRDL and TBLWTL instructions offer a direct method of reading or writing the lower word of any address within the program space, without going through data space. The TBLRDH and TBLWTH instructions are the only method to read or write the upper 8 bits of a program space word as data.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to data space addresses. Program memory can thus be regarded as two 16-bit, word-wide address spaces, residing side by side, each with the same address range. TBLRDL and TBLWTL access the space which contains the least significant data word, and TBLRDH and TBLWTH access the space which contains the upper data byte.

Two table instructions are provided to move byte or word-sized (16-bit) data to and from program space. Both function as either byte or word operations.

1. TBLRDL (Table Read Low): In Word mode, it maps the lower word of the program space location (P<15:0>) to a data address (D<15:0>).

   In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when byte select is '1'; the lower byte is selected when it is '0'.

2. TBLRDH (Table Read High): In Word mode, it maps the entire upper word of a program address (P<23:16>) to a data address. Note that D<15:8>, the "phantom byte", will always be '0'.

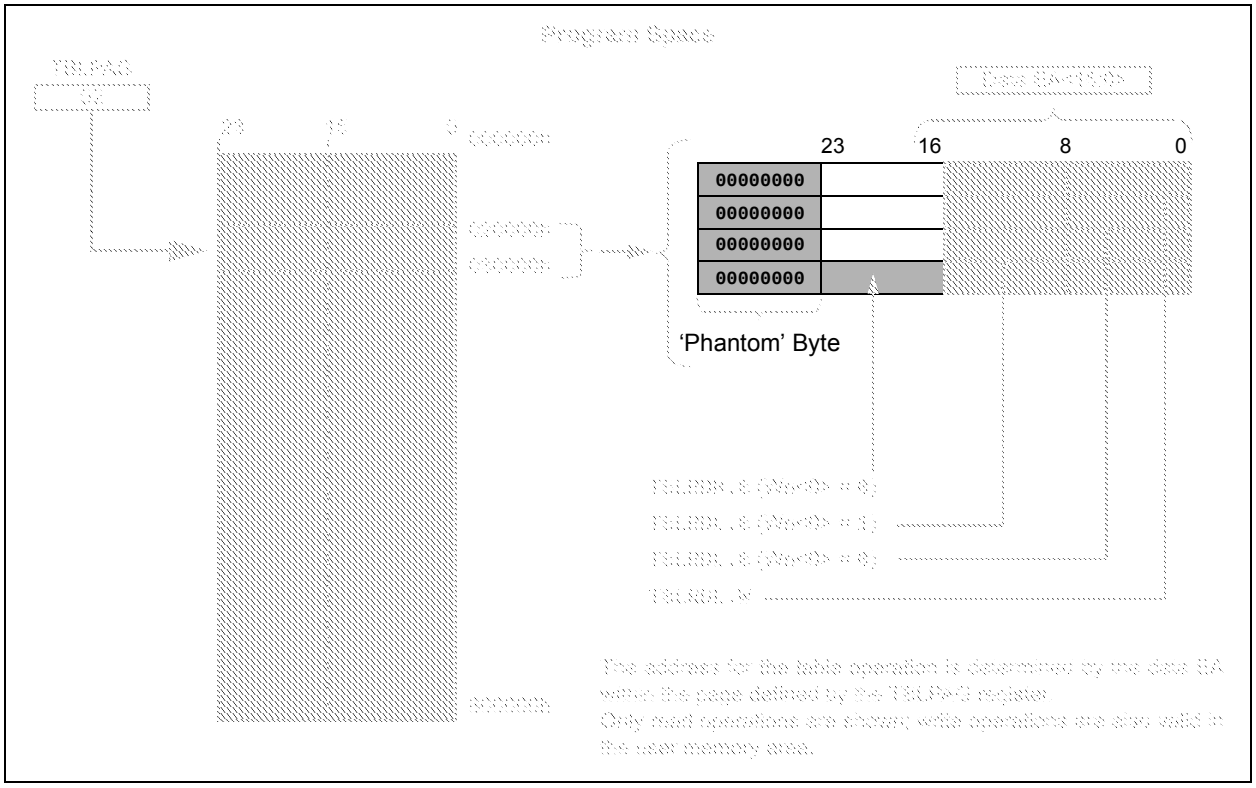
   In Byte mode, it maps the upper or lower byte of the program word to D<7:0> of the data address, as above. Note that the data will always be '0' when the upper "phantom" byte is selected (byte select = 1).

In a similar fashion, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a program space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Page register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user and configuration spaces. When TBLPAG<7> = 0, the Table Page is located in the user memory space. When TBLPAG<7> = 1, the page is located in configuration space.

Note:	Only table read operations will execute in the configuration memory space, and only then, in implemented areas such as the Device ID. Table write operations are not allowed.

FIGURE 4-6: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS



4.3.3 READING DATA FROM PROGRAM MEMORY USING PROGRAM SPACE VISIBILITY

The upper 32 Kbytes of data space may optionally be mapped into any 16K word page of the program space. This provides transparent access of stored constant data from the data space without the need to use special instructions (i.e., TBLRDL/H).

Program space access through the data space occurs if the Most Significant bit of the data space EA is '1' and Program Space Visibility is enabled by setting the PSV bit in the Core Control register (CORCON<2>). The location of the program memory space to be mapped into the data space is determined by the Program Space Visibility Page register (PSVPAG). This 8-bit register defines any one of 256 possible pages of 16K words in program space. In effect, PSVPAG functions as the upper 8 bits of the program memory address, with the 15 bits of the EA functioning as the lower bits. Note that by incrementing the PC by 2 for each program memory word, the lower 15 bits of data space addresses directly map to the lower 15 bits in the corresponding program space addresses.

Data reads to this area add an additional cycle to the instruction being executed, since two program memory fetches are required.

Although each data space address, 8000h and higher, maps directly into a corresponding program memory address (see Figure 4-7), only the lower 16 bits of the 24-bit program word are used to contain the data. The upper 8 bits of any program space locations used as data should be programmed with '1111 1111' or '0000 0000' to force a NOP. This prevents possible issues should the area of code ever be accidentally executed.

Note:	PSV access is temporarily disabled during table reads/writes.

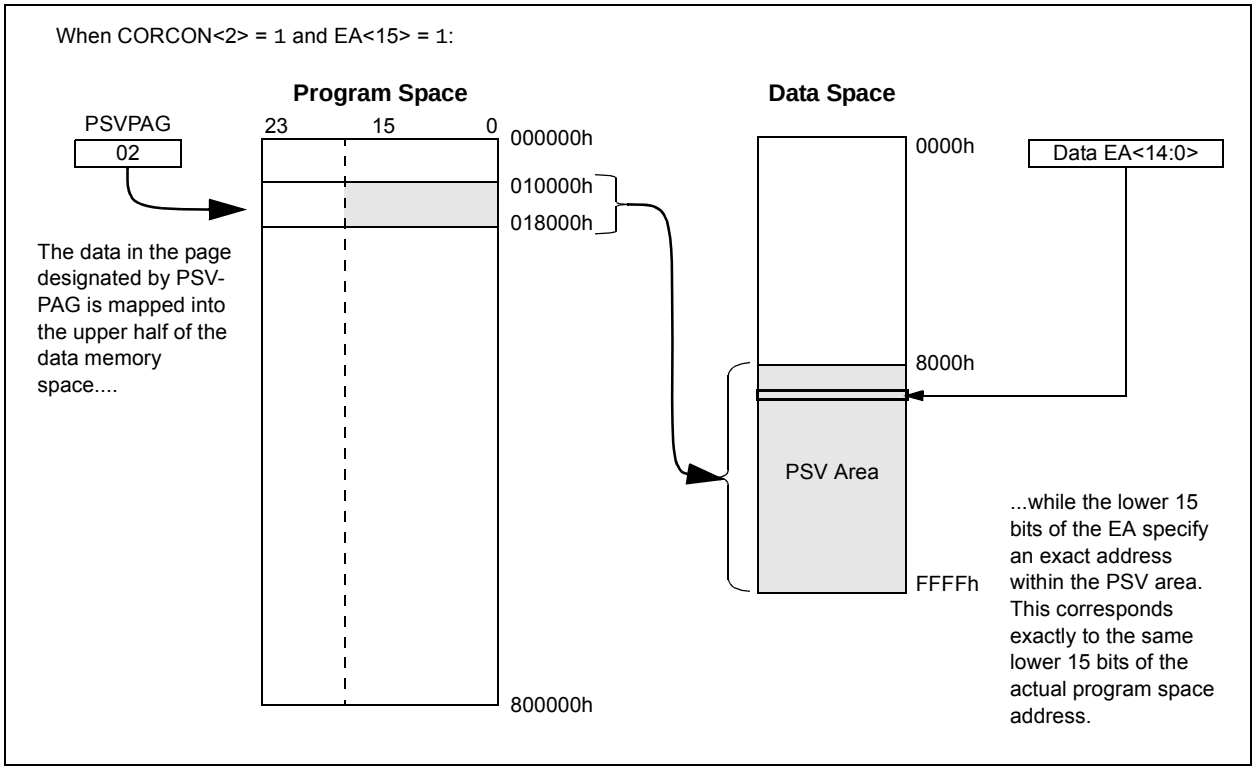
For operations that use PSV and are executed outside a REPEAT loop, the MOV and MOV.D instructions will require one instruction cycle in addition to the specified execution time. All other instructions will require two instruction cycles in addition to the specified execution time.

For operations that use PSV which are executed inside a REPEAT loop, there will be some instances that require two instruction cycles in addition to the specified execution time of the instruction:

- Execution in the first iteration
- Execution in the last iteration
- Execution prior to exiting the loop due to an interrupt
- Execution upon re-entering the loop after an interrupt is serviced

Any other iteration of the REPEAT loop will allow the instruction accessing data, using PSV, to execute in a single cycle.

FIGURE 4-7: PROGRAM SPACE VISIBILITY OPERATION



REGISTER 8-2: CLKDIV: CLOCK DIVIDER REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1
ROI	DOZE2	DOZE1	DOZE0	DOZEN(1)	RCDIV2	RCDIV1	RCDIV0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ROI:** Recover on Interrupt bit
1 = Interrupts clear the DOZEN bit and reset the CPU peripheral clock ratio to 1:1
0 = Interrupts have no effect on the DOZEN bit

bit 14-12 **DOZE<2:0>:** CPU Peripheral Clock Ratio Select bits
111 = 1:128
110 = 1:64
101 = 1:32
100 = 1:16
011 = 1:8
010 = 1:4
001 = 1:2
000 = 1:1

bit 11 **DOZEN:** DOZE Enable bit(1)
1 = DOZE<2:0> bits specify the CPU peripheral clock ratio
0 = CPU peripheral clock ratio set to 1:1

bit 10-8 **RCDIV<2:0>:** FRC Postscaler Select bits
111 = 31.25 kHz (divide-by-256)
110 = 125 kHz (divide-by-64)
101 = 250 kHz (divide-by-32)
100 = 500 kHz (divide-by-16)
011 = 1 MHz (divide-by-8)
010 = 2 MHz (divide-by-4)
001 = 4 MHz (divide-by-2)
000 = 8 MHz (divide-by-1)

bit 7-0 **Unimplemented:** Read as '0'

Note 1: This bit is automatically cleared when the ROI bit is set and an interrupt occurs.

9.0 POWER-SAVING FEATURES

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. Refer to **Section 10. Power-Saving Features"** (DS39698) in the *"PIC24F Family Reference Manual"* for more information.

The PIC24FJ128GA010 family of devices provides the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. All PIC24F devices manage power consumption in four different ways:

- Clock Frequency
- Instruction-Based Sleep and Idle modes
- Software-Controlled Doze mode
- Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption, while still maintaining critical application features, such as timing-sensitive communications.

9.1 Clock Frequency and Clock Switching

PIC24F devices allow for a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSC bits. The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 8.0 "Oscillator Configuration"**.

9.2 Instruction-Based Power-Saving Modes

PIC24F devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution; Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembly syntax of the PWRSAV instruction is shown in Example 9-1.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

9.2.1 SLEEP MODE

Sleep mode has these features:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption will be reduced to a minimum provided that no I/O pin is sourcing current.
- The Fail-Safe Clock Monitor does not operate during Sleep mode since the system clock source is disabled.
- The LPRC clock will continue to run in Sleep mode if the WDT is enabled.
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode.
- Some device features or peripherals may continue to operate in Sleep mode. This includes items, such as the input change notification on the I/O ports, or peripherals that use an external clock input. Any peripheral that requires the system clock source for its operation will be disabled in Sleep mode.

The device will wake-up from Sleep mode on any of these events:

- On any interrupt source that is individually enabled
- On any form of device Reset
- On a WDT time-out

On wake-up from Sleep, the processor will restart with the same clock source that was active when Sleep mode was entered.

EXAMPLE 9-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV#SLEEP_MODE  ; Put the device into SLEEP mode
PWRSAV#IDLE_MODE   ; Put the device into IDLE mode
```

10.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORT, LAT and TRIS registers for data control, each port pin can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs higher than VDD (e.g., 5V) on any desired digital only pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum VIH specification.

10.2 Configuring Analog Port Pins

The use of the AD1PCFG and TRIS registers control the operation of the A/D port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bit set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

When reading the PORT register, all pins configured as analog input channels will read as cleared (a low level).

Pins configured as digital inputs will not convert an analog input. Analog levels on any pin that is defined as a digital input (including the ANx pins) may cause the input buffer to consume current that exceeds the device specifications.

10.2.1 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be a NOP.

10.2.2 ANALOG INPUT PINS AND VOLTAGE CONSIDERATIONS

The voltage tolerance of pins used as device inputs is dependent on the pin's input function. Pins that are used as digital only inputs are able to handle DC voltages up to 5.5V, a level typical for digital logic circuits. In contrast, pins that also have analog input functions of any kind can only tolerate voltages up to VDD. On these pins, voltage excursions beyond VDD are always to be avoided. Table 10-1 summarizes the input capabilities. Refer to **Section 27.1 "DC Characteristics"** for more details.

Note:	For easy identification, the pin diagrams at the beginning of this data sheet also indicate 5.5V tolerant pins with dark grey shading.

TABLE 10-1: INPUT VOLTAGE LEVELS(1)

Port or Pin	Tolerated Input	Description
PORTA<10:9>	VDD	Only VDD input levels are tolerated.
PORTB<15:0>		
PORTC<15:12>		
PORTA<15:14>	5.5V	Tolerates input levels above VDD, useful for most standard logic.
PORTA<7:0>		
PORTC<4:1>		
PORTD<15:0>		
PORTE<9:0>		
PORTF<13:12>		
PORTF<8:0>		
PORTG<15:12>		
PORTG<9:6>		
PORTG<3:0>		

Note 1: Not all port pins shown here are implemented on 64-pin and 80-pin devices. Refer to **Section 1.0 "Device Overview"** to confirm which ports are available in specific devices.

EXAMPLE 10-1: PORT WRITE/READ EXAMPLE

```
MOV   0xFF00, W0          ; Configure PORTB<15:8> as inputs
MOV   W0, TRISBB          ; and PORTB<7:0> as outputs
NOP                       ; Delay 1 cycle
btss  PORTB, #13          ; Next Instruction
```

13.0 INPUT CAPTURE

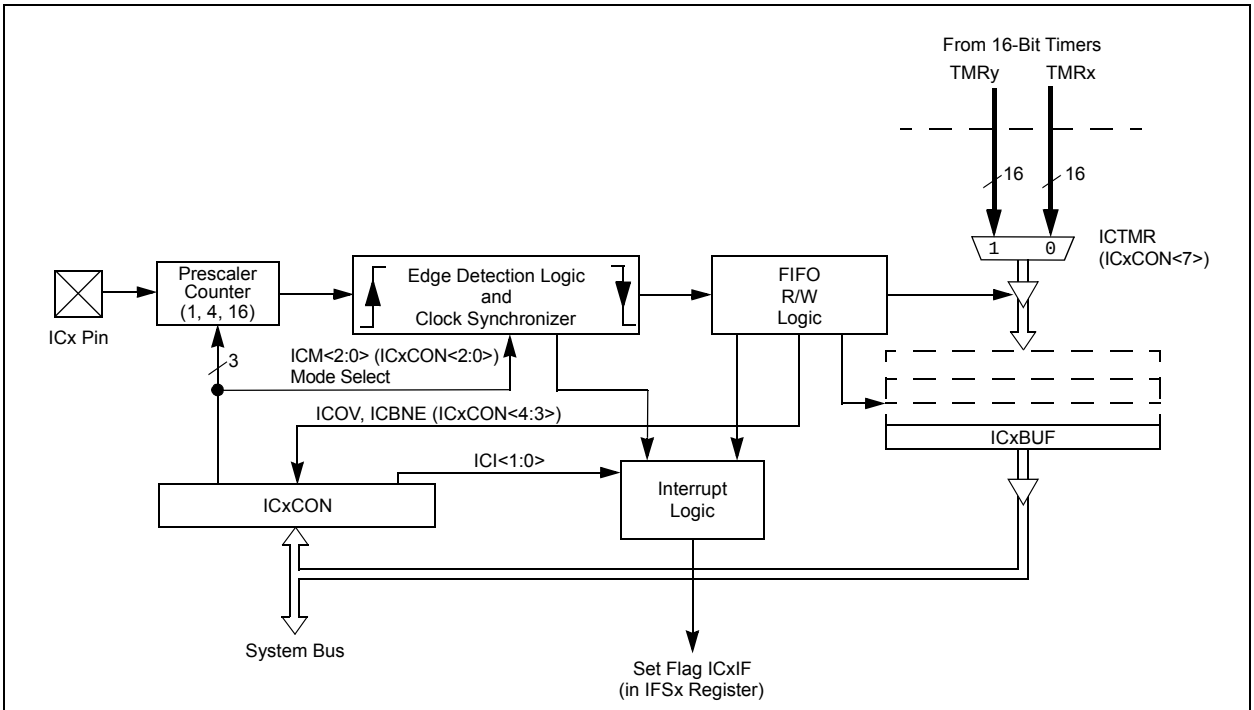
Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. Refer to **Section 15. "Input Capture"** (DS39701) in the *"PIC24F Family Reference Manual"* for more information.

The input capture module has multiple operating modes, which are selected via the ICxCON register. The operating modes include:

- Capture timer value on every falling edge of input, applied at the ICx pin
- Capture timer value on every rising edge of input, applied at the ICx pin
- Capture timer value on every fourth rising edge of input, applied at the ICx pin
- Capture timer value on every 16th rising edge of input, applied at the ICx pin
- Capture timer value on every rising and every falling edge of input, applied at the ICx pin
- Device wake-up from capture pin during CPU Sleep and Idle modes

The input capture module has a four-level FIFO buffer. The number of capture events required to generate a CPU interrupt can be selected by the user.

FIGURE 13-1: INPUT CAPTURE BLOCK DIAGRAM



Note: An 'x' in a signal, register or bit name denotes the number of the capture channel.

FIGURE 18-2: LEGACY PARALLEL SLAVE PORT EXAMPLE

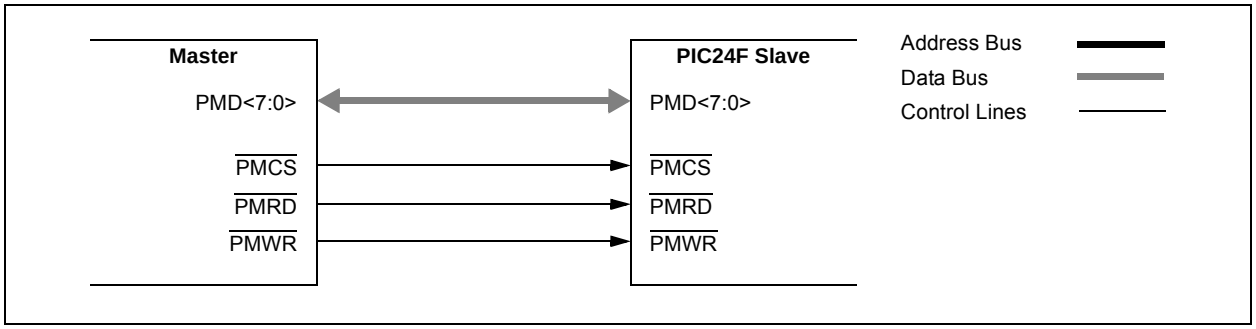


FIGURE 18-3: ADDRESSABLE PARALLEL SLAVE PORT EXAMPLE

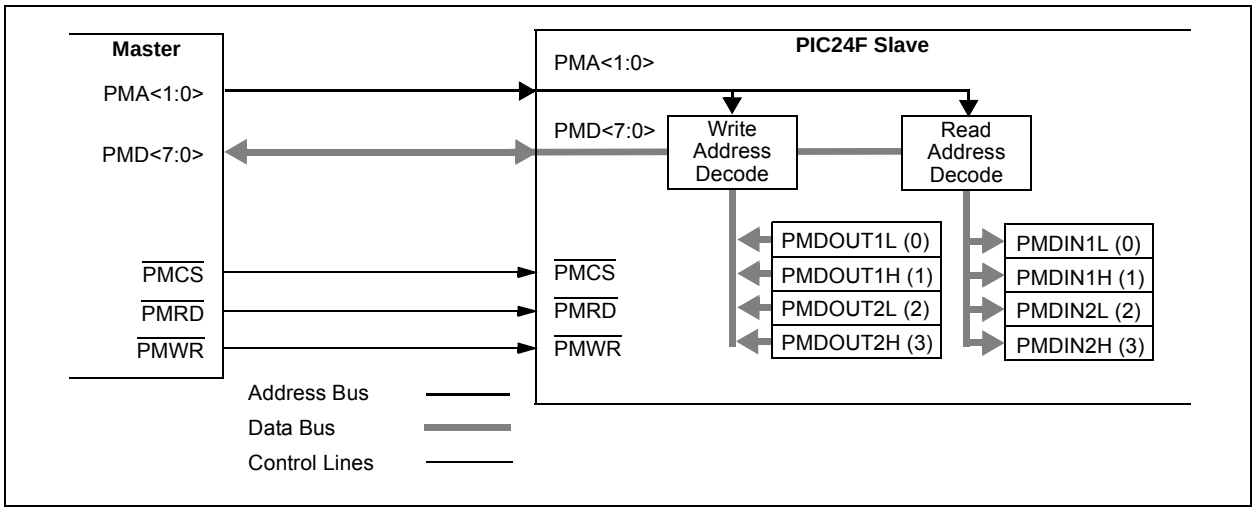
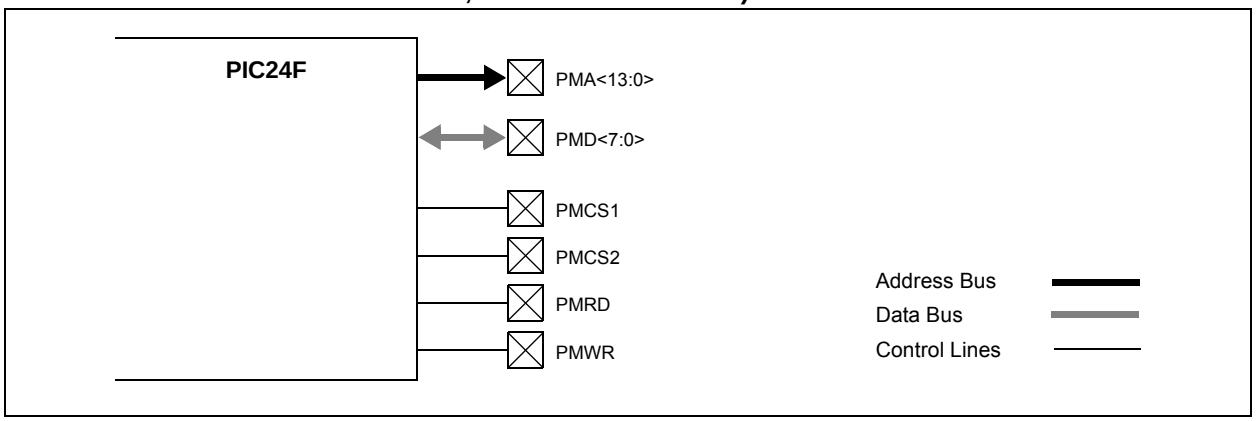


TABLE 18-1: SLAVE MODE ADDRESS RESOLUTION

PMA<1:0>	Output Register (Buffer)	Input Register (Buffer)
00	PMDOUT1<7:0> (0)	PMDIN1<7:0> (0)
01	PMDOUT1<15:8> (1)	PMDIN1<15:8> (1)
10	PMDOUT2<7:0> (2)	PMDIN2<7:0> (2)
11	PMDOUT2<15:8> (3)	PMDIN2<15:8> (3)

FIGURE 18-4: MASTER MODE, DEMULTIPLEXED ADDRESSING (SEPARATE READ AND WRITE STROBES, TWO CHIP SELECTS)



REGISTER 21-2: AD1CON2: A/D CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	U-0	U-0
VCFG2	VCFG1	VCFG0	r	—	CSCNA	—	—
bit 15							bit 8

R-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
BUFS	—	SMPI3	SMPI2	SMPI1	SMPI0	BUFM	ALTS
bit 7							bit 0

Legend:	r = Reserved bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **VCFG<2:0>:** Voltage Reference Configuration bits:

VCFG<2:0>	VR+	VR-
000	AVDD	AVSS
001	External VREF+ pin	AVSS
010	AVDD	External VREF- pin
011	External VREF+ pin	External VREF- pin
1xx	AVDD	AVSS

bit 12 **Reserved**

bit 11 **Unimplemented:** Read as '0'

bit 10 **CSCNA:** Scan Input Selections for CH0+ S/H Input for MUX A Input Multiplexor Setting bit
1 = Scan inputs
0 = Do not scan inputs

bit 9-8 **Unimplemented:** Read as '0'

bit 7 **BUFS:** Buffer Fill Status bit (valid only when BUFM = 1)
1 = A/D is currently filling Buffer 08-0F, user should access data in 00-07
0 = A/D is currently filling Buffer 00-07, user should access data in 08-0F

bit 6 **Unimplemented:** Read as '0'

bit 5-2 **SMPI<3:0>:** Sample/Convert Sequences Per Interrupt Selection bits
1111 = Interrupts at the completion of conversion for each 16th sample/convert sequence
1110 = Interrupts at the completion of conversion for each 15th sample/convert sequence
.....
0001 = Interrupts at the completion of conversion for each 2nd sample/convert sequence
0000 = Interrupts at the completion of conversion for each sample/convert sequence

bit 1 **BUFM:** Buffer Mode Select bit
1 = Buffer configured as two 8-word buffers (ADC1BUFx<15:8> and ADC1BUFx<7:0>)
0 = Buffer configured as one 16-word buffer (ADC1BUFx<15:0>)

bit 0 **ALTS:** Alternate Input Sample Mode Select bit
1 = Uses MUX A input multiplexor settings for the first sample, then alternates between the MUX B and MUX A input multiplexor settings for all subsequent samples
0 = Always uses MUX A input multiplexor settings

REGISTER 22-1: CMCON: COMPARATOR CONTROL REGISTER (CONTINUED)

bit 5 **C2INV:** Comparator 2 Output Inversion bit
1 = C2 output is inverted
0 = C2 output is not inverted

bit 4 **C1INV:** Comparator 1 Output Inversion bit
1 = C1 output is inverted
0 = C1 output is not inverted

bit 3 **C2NEG:** Comparator 2 Negative Input Configure bit
1 = C2IN+ is connected to VIN-
0 = C2IN- is connected to VIN-
See Figure 22-1 for the Comparator modes.

bit 2 **C2POS:** Comparator 2 Positive Input Configure bit
1 = C2IN+ is connected to VIN+
0 = CVREF is connected to VIN+
See Figure 22-1 for the Comparator modes.

bit 1 **C1NEG:** Comparator 1 Negative Input Configure bit
1 = C1IN+ is connected to VIN-
0 = C1IN- is connected to VIN-
See Figure 22-1 for the Comparator modes.

bit 0 **C1POS:** Comparator 1 Positive Input Configure bit
1 = C1IN is connected to VIN+
0 = CVREF is connected to VIN+
See Figure 22-1 for the Comparator modes.

23.0 COMPARATOR VOLTAGE REFERENCE

Note:	This data sheet summarizes features of PIC24F group of devices and is not intended to be a comprehensive reference source. Refer to **Section 20. "Comparator Voltage Reference Module"** (DS39709) in the *"PIC24F Family Reference Manual"* for more information.

23.1 Configuring the Comparator Voltage Reference

The voltage reference module is controlled through the CVRCON register (Register 23-1). The comparator voltage reference provides two ranges of output voltage, each with 16 distinct levels. The range to be used is selected by the CVRR bit (CVRCON<5>). The primary difference between the ranges is the size of the steps selected by the CVREF Selection bits (CVR<3:0>), with one range offering finer resolution.

The comparator reference supply voltage can come from either VDD and VSS, or the external VREF+ and VREF-. The voltage source is selected by the CVRSS bit (CVRCON<4>).

The settling time of the comparator voltage reference must be considered when changing the CVREF output.

CVRR: Comparator VREF Range Selection bit 1 = 0 to 0.625 CVRSRC, with CVRSRC/24 step size.

0 = 0.25 CVRSRC to 0.72 CVRSRC, with CVRSRC/32 step size

FIGURE 23-1: COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM

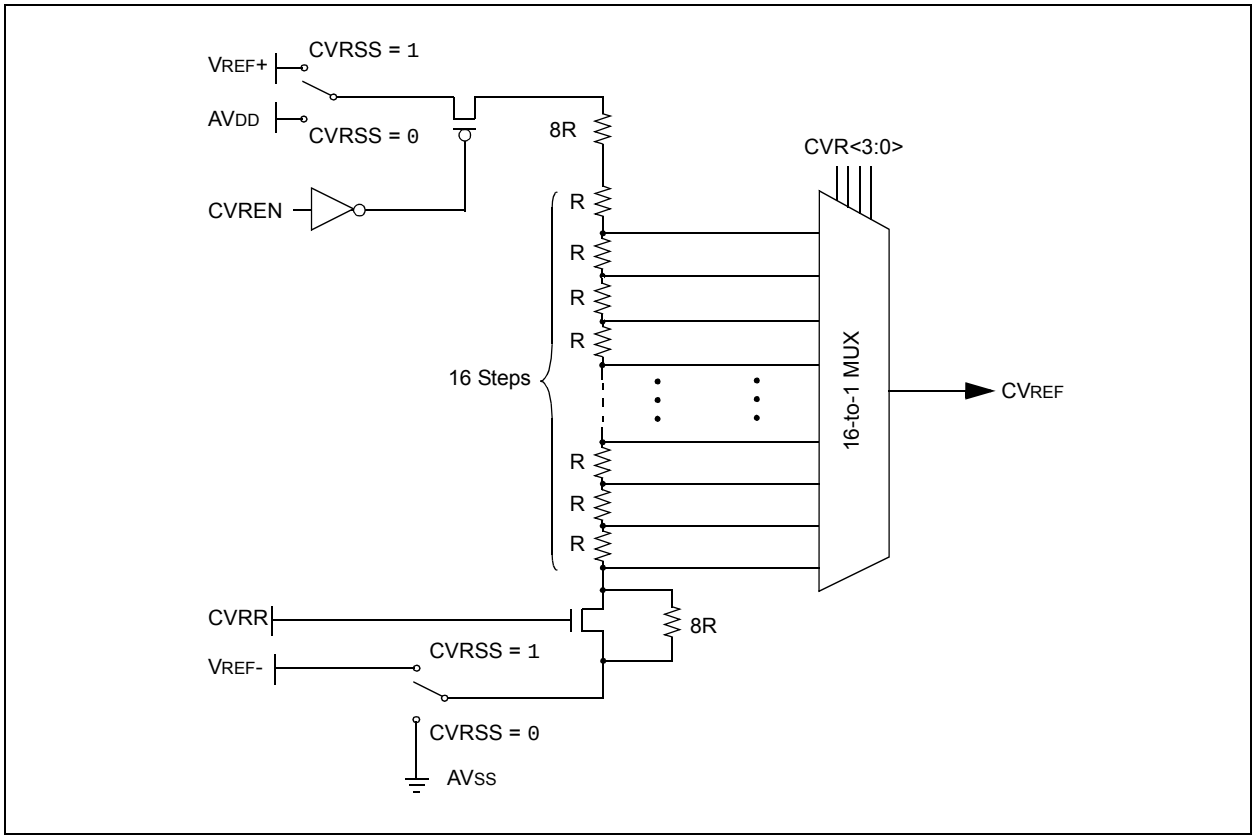


TABLE 25-2: INSTRUCTION SET OVERVIEW

Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles	Status Flags Affected
ADD	ADD	f	f = f + WREG	1	1	C, DC, N, OV, Z
	ADD	f,WREG	WREG = f + WREG	1	1	C, DC, N, OV, Z
	ADD	#lit10,Wn	Wd = lit10 + Wd	1	1	C, DC, N, OV, Z
	ADD	Wb,Ws,Wd	Wd = Wb + Ws	1	1	C, DC, N, OV, Z
	ADD	Wb,#lit5,Wd	Wd = Wb + lit5	1	1	C, DC, N, OV, Z
ADDC	ADDC	f	f = f + WREG + (C)	1	1	C, DC, N, OV, Z
	ADDC	f,WREG	WREG = f + WREG + (C)	1	1	C, DC, N, OV, Z
	ADDC	#lit10,Wn	Wd = lit10 + Wd + (C)	1	1	C, DC, N, OV, Z
	ADDC	Wb,Ws,Wd	Wd = Wb + Ws + (C)	1	1	C, DC, N, OV, Z
	ADDC	Wb,#lit5,Wd	Wd = Wb + lit5 + (C)	1	1	C, DC, N, OV, Z
AND	AND	f	f = f .AND. WREG	1	1	N, Z
	AND	f,WREG	WREG = f .AND. WREG	1	1	N, Z
	AND	#lit10,Wn	Wd = lit10 .AND. Wd	1	1	N, Z
	AND	Wb,Ws,Wd	Wd = Wb .AND. Ws	1	1	N, Z
	AND	Wb,#lit5,Wd	Wd = Wb .AND. lit5	1	1	N, Z
ASR	ASR	f	f = Arithmetic Right Shift f	1	1	C, N, OV, Z
	ASR	f,WREG	WREG = Arithmetic Right Shift f	1	1	C, N, OV, Z
	ASR	Ws,Wd	Wd = Arithmetic Right Shift Ws	1	1	C, N, OV, Z
	ASR	Wb,Wns,Wnd	Wnd = Arithmetic Right Shift Wb by Wns	1	1	N, Z
	ASR	Wb,#lit5,Wnd	Wnd = Arithmetic Right Shift Wb by lit5	1	1	N, Z
BCLR	BCLR	f,#bit4	Bit Clear f	1	1	None
	BCLR	Ws,#bit4	Bit Clear Ws	1	1	None
BRA	BRA	C,Expr	Branch if Carry	1	1 (2)	None
	BRA	GE,Expr	Branch if Greater than or Equal	1	1 (2)	None
	BRA	GEU,Expr	Branch if Unsigned Greater than or Equal	1	1 (2)	None
	BRA	GT,Expr	Branch if Greater than	1	1 (2)	None
	BRA	GTU,Expr	Branch if Unsigned Greater than	1	1 (2)	None
	BRA	LE,Expr	Branch if Less than or Equal	1	1 (2)	None
	BRA	LEU,Expr	Branch if Unsigned Less than or Equal	1	1 (2)	None
	BRA	LT,Expr	Branch if Less than	1	1 (2)	None
	BRA	LTU,Expr	Branch if Unsigned Less than	1	1 (2)	None
	BRA	N,Expr	Branch if Negative	1	1 (2)	None
	BRA	NC,Expr	Branch if Not Carry	1	1 (2)	None
	BRA	NN,Expr	Branch if Not Negative	1	1 (2)	None
	BRA	NOV,Expr	Branch if Not Overflow	1	1 (2)	None
	BRA	NZ,Expr	Branch if Not Zero	1	1 (2)	None
	BRA	OV,Expr	Branch if Overflow	1	1 (2)	None
	BRA	Expr	Branch Unconditionally	1	2	None
	BRA	Z,Expr	Branch if Zero	1	1 (2)	None
	BRA	Wn	Computed Branch	1	2	None
BSET	BSET	f,#bit4	Bit Set f	1	1	None
	BSET	Ws,#bit4	Bit Set Ws	1	1	None
BSW	BSW.C	Ws,Wb	Write C bit to Ws<Wb>	1	1	None
	BSW.Z	Ws,Wb	Write Z bit to Ws<Wb>	1	1	None
BTG	BTG	f,#bit4	Bit Toggle f	1	1	None
	BTG	Ws,#bit4	Bit Toggle Ws	1	1	None
BTSC	BTSC	f,#bit4	Bit Test f, Skip if Clear	1	1 (2 or 3)	None
	BTSC	Ws,#bit4	Bit Test Ws, Skip if Clear	1	1 (2 or 3)	None

TABLE 25-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles	Status Flags Affected
TBLRDL	TBLRDL	Ws,Wd	Read Prog<15:0> to Wd	1	2	None
TBLWTH	TBLWTH	Ws,Wd	Write Ws<7:0> to Prog<23:16>	1	2	None
TBLWTL	TBLWTL	Ws,Wd	Write Ws to Prog<15:0>	1	2	None
ULNK	ULNK		Unlink Frame Pointer	1	1	None
XOR	XOR	f	f = f .XOR. WREG	1	1	N, Z
	XOR	f,WREG	WREG = f .XOR. WREG	1	1	N, Z
	XOR	#lit10,Wn	Wd = lit10 .XOR. Wd	1	1	N, Z
	XOR	Wb,Ws,Wd	Wd = Wb .XOR. Ws	1	1	N, Z
	XOR	Wb,#lit5,Wd	Wd = Wb .XOR. lit5	1	1	N, Z
ZE	ZE	Ws,Wnd	Wnd = Zero-Extend Ws	1	1	C, Z, N

TABLE 27-22: A/D MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C				
Param No.	Symbol	Characteristic	Min.	Typ	Max.	Units	Conditions
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of VDD – 0.3 or 2.0	—	Lesser of VDD + 0.3 or 3.6	V	
AD02	AVSS	Module VSS Supply	VSS – 0.3	—	VSS + 0.3	V	
Reference Inputs							
AD05	VREFH	Reference Voltage High	AVSS + 1.7	—	AVDD	V	
AD06	VREFL	Reference Voltage Low	AVSS	—	AVDD – 1.7	V	
AD07	VREF	Absolute Reference Voltage	AVSS – 0.3	—	AVDD + 0.3	V	
AD08	IVREF	Reference Voltage Input Current	—	—	1.25	mA	
AD09	ZVREF	Reference Input Impedance	—	10K	—	Ω	
Analog Input							
AD10	VINH-VINL	Full-Scale Input Span(2)	VREFL		VREFH	V	
AD11	VIN	Absolute Input Voltage	AVSS – 0.3		AVDD + 0.3	V	
AD12	—	Leakage Current	—	±0.001	±0.610	μA	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5V, Source Impedance = 2.5 kΩ
AD14	VINL	Absolute VINL Input Voltage	AVSS – 0.3		AVDD/2	V	
AD17	RIN	Recommended Impedance of Analog Voltage	—	—	2.5K		
A/D Accuracy							
AD20a	Nr	Resolution	10 data bits			bits	
AD21a	INL	Integral Nonlinearity(2)	—	±1	<±2	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3V
AD22a	DNL	Differential Nonlinearity(2)	—	±0.5	<±1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3V
AD23a	GERR	Gain Error(2)	—	±1	±3	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3V
AD24a	EOFF	Offset Error(2)	—	±1	±2	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3V
AD25a	—	Monotonicity(1)	—	—	—	—	Guaranteed

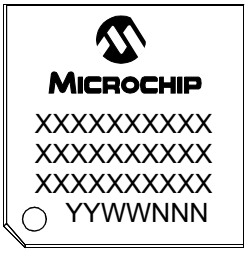
Note 1: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

2: Measurements are taken with external VREF+ and VREF- used as the A/D voltage reference.

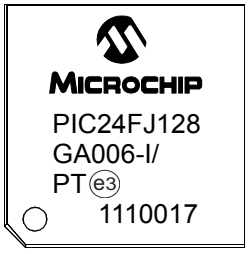
28.0 PACKAGING INFORMATION

28.1 Package Marking Information

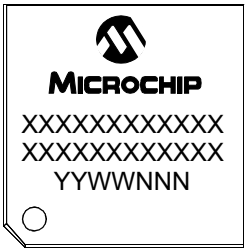
64-Lead TQFP (10x10x1 mm)



Example

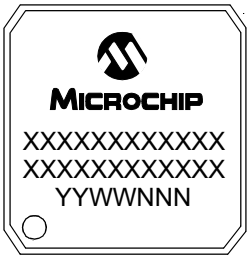


80-Lead TQFP (12x12x1 mm)



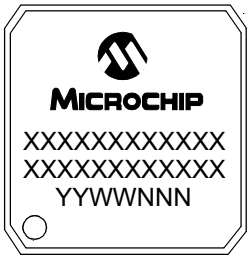
Example

100-Lead TQFP (12x12x1 mm)



Example

100-Lead TQFP (14x14x1 mm)



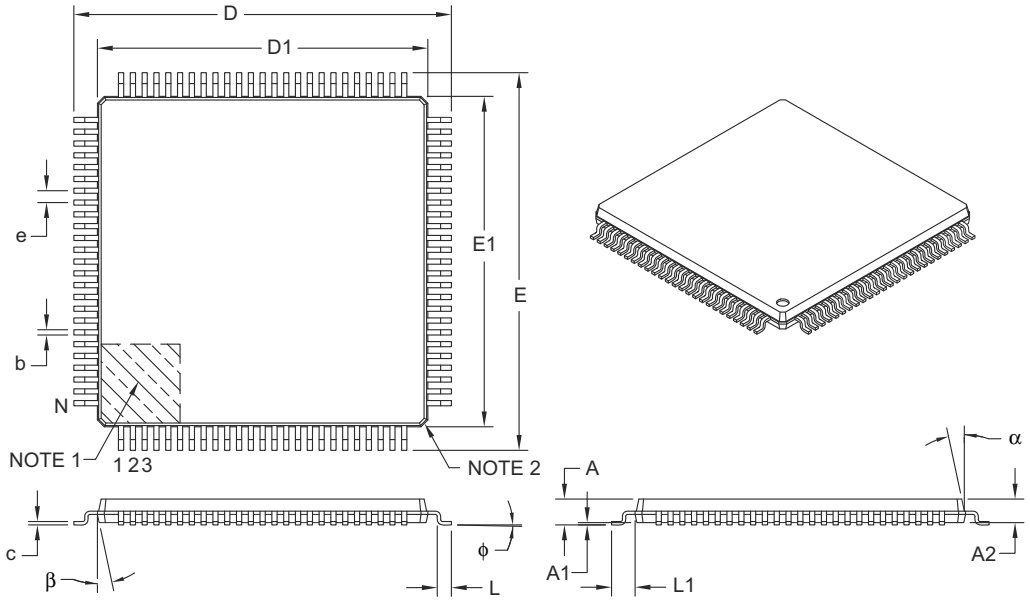
Example

Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
		Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

100-Lead Plastic Thin Quad Flatpack (PF) – 14x14x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		100	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		16.00 BSC	
Overall Length	D		16.00 BSC	
Molded Package Width	E1		14.00 BSC	
Molded Package Length	D1		14.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

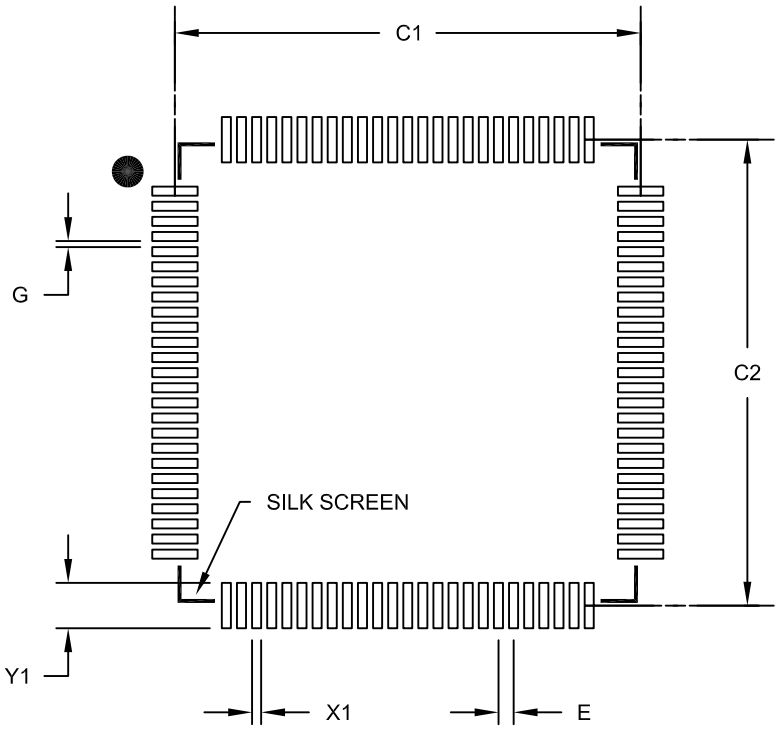
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-110B

100-Lead Plastic Thin Quad Flatpack (PF) - 14x14x1 mm Body 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		15.40	
Contact Pad Spacing	C2		15.40	
Contact Pad Width (X100)	X1			0.30
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2110B

NOTES:

NOTES: